

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Patent No. : 7,361,971 Confirmation No. 6221
Inventor : HIDEO SENOO
Issued : April 22, 2008
Title : SEMICONDUCTOR WAFER PROTECTION STRUCTURE
AND LAMINATED PROTECTIVE SHEET FOR USE THEREIN
Examiner : Cuong Quang Nguyen
Customer No. : 28289

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

ATTENTION: Decision and Certificate of Correction Branch
Patent Issue Division

REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT
FOR PTO MISTAKE (37 C.F.R. 1.322(a))

Sir:

In accordance with 35 U.S.C. §254, we attach hereto Form PTO/SB/44 and a copy of proof of PTO errors and request that a Certificate of Correction be issued in the above-identified patent. The following errors appear in the patent as printed:

Face of the Patent, see Item (56) References Cited, U.S. PATENT DOCUMENTS, insert the following two U.S. references:

5,637,395	B1	6/1997	Uemura et al.
6,910,403	B1	6/2005	Ishikawa et al.

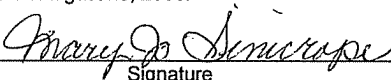
Face of the Patent, see Item (56) References Cited, FOREIGN PATENT DOCUMENTS, insert the following six Japanese references:

JP	60-223139 A	11/1985
JP	5-032946 A	2/1993
JP	8-027239 A	1/1996
JP	2005-057208 A	2/2002
JP	2003-129011 A	5/2003
JP	2003-261842 A	9/2003

(See the Information Disclosure Statement filed February 25, 2008 in Response to PTO Communication Re Information Disclosure Statement. The original IDS was filed on May 3, 2006 and was scanned into PAIR on May 9, 2006. A copy was faxed to the USPTO on January 3, 2008 because the Examiner failed to initial the originally filed IDS.

I hereby certify that this correspondence is being
electronically submitted to the United States Patent and
Trademark Office on August 26, 2008.

08/26/2008
Date


Signature

Mary Jo Sinicrope
Typed Name of Person Signing Certificate

Patent No. 7,361,971
Paper Dated: August 26, 2008
Attorney Docket No. 1217-050618

Column 12, line 41, "tolyene" should read – tolylene –
(See the Amendment dated February 27, 2007, page 4, line 3 of the replacement paragraph.)

Respectfully submitted,

THE WEBB LAW FIRM

By: 

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UNITED STATES PATENT AND TRADEMARK OFFICE CERTIFICATE OF CORRECTION

Page 1 of 1

PATENT NO. : 7,361,971
 APPLICATION NO. : 10/525,996
 ISSUE DATE : April 22, 2008
 INVENTORS : Senoo et al.

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Face of the Patent, see Item (56) References Cited, U.S. PATENT DOCUMENTS,
 insert the following two U.S. references:

5,637,395	B1	6/1997	Uemura et al.
6,910,403	B1	6/2005	Ishikawa et al.

Face of the Patent, see Item (56) References Cited, FOREIGN PATENT DOCUMENTS,
 insert the following six Japanese references:

JP	60-223139 A	11/1985
JP	5-032946 A	2/1993
JP	8-027239 A	1/1996
JP	2005-057208 A2/2002	
JP	2003-129011 A5/2003	
JP	2003-261842 A9/2003	

Column 12, line 41, "tolyene" should read – tolylene –

MAILING ADDRESS OF SENDER: The Webb Law Firm
 700 Koppers Building
 436 Seventh Avenue
 Pittsburgh, PA 15219

This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-2450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select Option 2.

Electronic Acknowledgement Receipt

EFS ID:	2901199
Application Number:	10525996
International Application Number:	
Confirmation Number:	6221
Title of Invention:	Semiconductor wafer protection structure and laminated protective sheet for use therein
First Named Inventor/Applicant Name:	Hideo Senoo
Correspondence Address:	Kent E Baldauf - 436 Seventh Avenue 700 Koppers Building Pittsburgh PA 15219-1818 US - -
Filer:	Kent E. Baldauf/Diane Paull
Filer Authorized By:	Kent E. Baldauf
Attorney Docket Number:	1217-050618
Receipt Date:	25-FEB-2008
Filing Date:	28-FEB-2005
Time Stamp:	07:31:15
Application Type:	U.S. National Stage under 35 USC 371

Payment information:

Submitted with Payment	no
File Listing:	

Document Number	Document Description	File Name	File Size(Bytes) Message Digest	Multi Part /.zip	Pages (if appl.)
1	Miscellaneous Incoming Letter	Response.pdf	357919	no	4
			7435ce267b5f3a20e08a1c1cab7bf2d4 e6644b34		

Warnings:

Information:

Total Files Size (in bytes):	357919
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This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.

Acknowledgement Receipt

The USPTO has received your submission at **07:31:15** Eastern Time on **25-FEB-2008** .

No fees have been paid for this submission. Please remember to pay any required fees on time to prevent abandonment of your application.

eFiled Application Information

EFS ID	2901199
Application Number	10525996
Confirmation Number	6221
Title	Semiconductor wafer protection structure and laminated protective sheet for use therein
First Named Inventor	Hideo Senoo
Customer Number or Correspondence Address	Kent E Baldauf 436 Seventh Avenue 700 Koppers Building Pittsburgh PA 15219-1818 US
Filed By	Kent E. Baldauf/Diane Paull
Attorney Docket Number	1217-050618
Filing Date	28-FEB-2005
Receipt Date	25-FEB-2008
Application Type	U.S. National Stage under 35 USC 371

Application Details

Submitted Files	Page Count	Document Description	File Size	Warnings
Response.pdf	4	Miscellaneous Incoming Letter	357919 bytes	◆ PASS

This Acknowledgement Receipt evidences receipt on the noted date by the USPTO of the indicated documents, characterized by the applicant, and including page counts, where applicable. It serves as evidence of receipt similar to a Post Card, as described in MPEP 503.

New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.

If you need help:

- *Call the Patent Electronic Business Center at (866) 217-9197 (toll free) or e-mail EBC@uspto.gov for specific questions about Patent e-Filing.*
- *Send general questions about USPTO programs to the [USPTO Contact Center \(UCC\)](#) .*
- *If you experience technical difficulties or problems with this application, please report them via e-mail to [Electronic Business Support](#) or call 1 800-786-9199.*

Notice of Allowance dated 12/13/2007

Appl. No. 10/525,996

Amdt. dated February 25, 2008

Attorney Docket No. 1217-050618

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/525,996 Confirmation No. 6221
Applicants : Hideo SENOO et al.
Filed : February 28, 2005
Title : Semiconductor Wafer Protection Structure and Laminated
Protective Sheet For Use Therein
Art Unit : 2811
Examiner : Cuong Quang Nguyen
Customer No. : 28289

MAIL STOP ISSUE FEE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

RESPONSE TO PTO COMMUNICATION RE INFORMATION DISCLOSURE STATEMENT

Sir:

A Notice of Allowance issued in the above-identified application on December 13, 2007. Upon final review of the prosecution history, it was noted that Applicants' Information Disclosure Statement filed May 3, 2006, had not been initialed and returned by the Examiner. A check of the records on Private PAIR indicated that the IDS had been received and scanned into PAIR on May 9, 2006. On January 3, 2008, Applicants faxed a copy of the May 3, 2006 Form PTO/SB/08a and requested that the Examiner initial and return a copy of the form to complete our records.

On February 14, 2008, the PTO issued an Office Communication indicating that the IDS filed 01-03-08 fails to comply with the rules because applicants do not give a reasonable reason for the delay in filing. Applicants were not attempting to file the IDS but, rather, were providing a copy of the IDS which was filed and scanned into the PTO records in May of 2006 but never initialed and returned to Applicants by the Examiner.

I hereby certify that this correspondence is being electronically submitted to the United States Patent and Trademark Office on February 25, 2008.

Diane Paul

(Name of Person Mailing Paper)

Diane Paul

Signature

02/25/2008

Date

Notice of Allowance dated 12/13/2007

Appl. No. 10/525,996

Amdt. dated February 25, 2008

Attorney Docket No. 1217-050618

Applicants respectfully request that the Examiner initial and return the attached copy of Form PTO/SB/08a originally submitted May 3, 2006. A copy of the return receipt postcard date-stamped by the PTO is also enclosed for verification.

Respectfully submitted,

THE WEBB LAW FIRM

By



Kent E. Baldauf

Registration No. 25,826

Attorney for Applicants

700 Koppers Building

436 Seventh Avenue

Pittsburgh, Pennsylvania 15219

Telephone: 412-471-8815

Facsimile: 412-471-4094

Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

Substitute for form 1449A/PTO				Complete if Known	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use as many sheets as necessary)				Application Number	10/525,996
				Filing Date	Feb. 28, 2005
				First Named Inventor	Hideo SENOO
				Art Unit	2811
				Examiner Name	Cuong Quang Nguyen
Sheet	1	of	1	Attorney Docket Number	1217-050618

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
		US- 5,637,395 B1	06-10-1997	Uemura et al.	
		US- 6,910,403 B1	06-28-2005	Ishikawa et al.	
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FOREIGN PATENT DOCUMENTS							
Examiner Initials*	Cite No. ¹	Foreign Patent Document		Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
		Country Code ³	Number ⁴ Kind Code ⁵ (if known)				
		JP(1985)	60-223139 A	11-07-1985	Nitto Electric Ind. Co.	English Abstract attached	
		JP(1993)	5-032946 A	02-09-1993	Lintec Corp.	English Abstract attached	
		JP(1996)	8-027239 A	01-30-1996	Lintec Corp.	English Abstract attached	
		JP(2002)	2005-057208 A	02-22-2002	Nitto Denko Corp.	English Abstract attached	
		JP(2003)	2003-129011 A	05-08-2003	Lintec Corp.	English Abstract attached	
		JP(2003)	2003-261842 A	09-19-2003	Lintec Corp.	English Abstract attached	

Examiner Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. ¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

This collection of information is required by 37 CFR 1.97 and 1.98. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 2 hours to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2

The dating stamp of the Patent Office on this card will be taken as an indication that the accompanying paper was filed.

Applicants: Hideo Senoo et al.

Appl. No. 10/525,996

Paper dated May 3, 2006

Atty's File No. 1217-050618

Amount of Check N/A

KEB/dp

{W0227140.1}

In re Patent Application entitled
"Protective Structure of Semiconductor
Wafer, Method for Protecting..."

Transmittal Form PTO/SB/21;
Information Disclosure Statement
(1 p.-in dupl.);
Form PTO/SB/08A (1 p.); and
copies of Japanese references
with English Abstract attached



Appl. No. 10/525,996
Amdt. dated February 20, 2007
Reply to Office Action of October 20, 2006
Attorney Docket No. 1217-050618

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.	:	10/525,996	Confirmation No. 6221
Applicants	:	Hideo SENOO et al.	
Filed	:	February 28, 2005	
Title	:	Semiconductor Wafer Protection Structure and Laminated Protective Sheet for Use Therein	
Art Unit	:	2811	
Examiner	:	Cuong Q. Nguyen	
Customer No.	:	28289	

MAIL STOP AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

In response to the Office Action of October 20, 2006, Applicants submit the following amendments and remarks along with a one-month Petition for Extension of Time and requisite fee.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 5 of this paper.

Remarks begin on page 9 of this paper.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on February 20, 2007.

Diane Paull

(Name of Person Mailing Paper)

Diane Paull
Signature

02/20/2007
Date

Please replace the paragraph beginning at page 32, line 13, with the following rewritten paragraph:

3 -- An energy radiation-curable copolymer having an energy radiation polymerizable group at a side chain was compounded with 5 parts by weight of a curing agent (addition product of ~~teluylene~~ tolyene diisocyanate and trimethylolpropane) and 5 parts by ~~weight~~ weight of a photopolymerization initiator (IRGACURE 184 manufactured by CIBA SPECIALTY CHEMICALS) to prepare a PSA. The above energy radiation-curable copolymer had been obtained by reaction of 100 parts by weight of a copolymer that consisted of 85 parts by weight of n-butyl acrylate and 15 parts by weight of 2-hydroxyethyl acrylate and had a weight-average molecular weight of about 650000, with 16 parts by weight of methacryloyloxyethyl isocyanate. The thus-obtained PSA was applied to a PET release film (SP-PET 3801 manufactured by LINTEC CORPORATION, thickness: 38 μm) with use of a roll knife coater so as to achieve a dry thickness of 15 μm , followed by drying. The resultant adhesive layer was transferred to the stress relaxation film prepared in (1). Thus, a first protective layer 1 was prepared. --